

# **Product Change Notification: ALAN-14RMFV263**

Date:

28-Apr-2025

## **Product Category:**

32-Bit Microcontrollers, Smart Energy Wireless Communications, Wireless Modules

# **Notification Subject:**

CCB 7531 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAM3S2A, ATSAM3S4A, ATSAM3S1A, ATSAM3N00A, ATSAM3N1A, ATSAM3N0A, AT91SAM7S32, AT86RF215M, ATmega1284RFR2, ATmega2564RFR2, ATmega644RFR2, AT86RF215, AT86RF215IQ, ATSAM4LS8A, ATSAM4LC8A, AT91SAM7S321, and ATSAM3N0AA device families available in 48L VQFN (7x7x1.0mm) package at MMT assembly site.

### **Affected CPNs:**

ALAN-14RMFV263\_Affected\_CPN\_04282025.pdf ALAN-14RMFV263\_Affected\_CPN\_04282025.csv

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected ATSAM3S2A, ATSAM3S4A, ATSAM3S1A, ATSAM3N0A, ATSAM3N0A, ATSAM3N0A, AT91SAM7S32, AT86RF215M, ATmega1284RFR2, ATmega2564RFR2, ATmega644RFR2, AT86RF215, AT86RF215IQ, ATSAM4LS8A, ATSAM4LC8A, AT91SAM7S321, and ATSAM3N0AA device families available in 48L VQFN (7x7x1.0mm) package at MMT assembly site.

## **Pre and Post Summary Changes:**

	Pre Change	Post Change
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Assembly Site	Microchip Technolog Thailand (Branch) (MMT)	y	Microchip Technology Thailand (Branch) (MMT)				
Wire Material	Au		CuPdAu				
Die Attach Material	3280		3280				
Molding Compound Material	G700LTD		G700LTD				
Lead-Frame Material	C194		C194				
DAP Surface Prep	Bare Cu	Ag-RT	Ag-RT				

Impacts to Datasheet: None

**Change Impact:** None

**Reason for Change:** To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire as a new wire material.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** July 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## **Timetable Summary:**

	April 2025				>	July 2025					
Work Week	14	15	16	17	18		27	28	29	30	31
Initial PCN Issue Date					X						
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN # Qual Plan.

Revision History: April 28, 2025: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

#### **Attachments:**

PCN\_ALAN-14RMFV263-Qual-Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> <u>home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.